

P-Channel Enhancement Mode MOSFET

TDM3435

DESCRIPTION

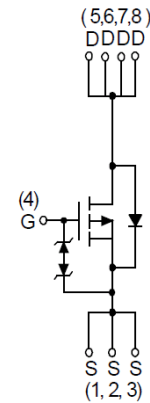
The TDM3435 uses advanced trench technology to provide excellent RDS(ON) and low gate charge. This device is suitable for use as a load switch or in PWM applications.

GENERAL FEATURES

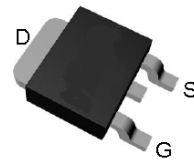
- -30V/-68A
- RDS(ON) < 15mΩ @ VGS=-4.5V
RDS(ON) < 9mΩ @ VGS=-10V
- Reliable and Rugged
- HBM ESD capability level of 8KV typical
- Lead free product is available
- TO252 Package

Application

- PWM applications
- Load switch
- Power management



P-Channel MOSFET



Top View of TO-252-3

ABSOLUTE MAXIMUM RATINGS($T_A=25^{\circ}\text{C}$ unless otherwise noted)

Parameter	Symbol	Rating	Unit
Drain-Source Voltage	V_{DS}	-30	V
Gate-Source Voltage	V_{GS}	± 25	V
Diode Continuous Forward Current	$I_S(T_C=25^{\circ}\text{C})$	-30	A
Pulsed Drain Current Tested (note1)	$I_{DM}(T_C=25^{\circ}\text{C})$	-180	A
Continuous Drain Current	$I_D(T_C=25^{\circ}\text{C})$	-68	A
	$I_D(T_C=100^{\circ}\text{C})$	-43	A
Maximum Power Dissipation	$P_D(T_C=25^{\circ}\text{C})$	62.5	W
	$P_D(T_C=100^{\circ}\text{C})$	25	W
Continuous Drain Current($V_{GS}=-10\text{V}$) (note1)	$I_D(T_A=25^{\circ}\text{C})$	-21.5	A
	$I_D(T_A=70^{\circ}\text{C})$	-17.2	A
Maximum Power Dissipation	$P_D(T_A=25^{\circ}\text{C})$	6.25	W
	$P_D(T_A=70^{\circ}\text{C})$	4	W
Thermal Resistance-Junction to Ambient (note1)	$R_{\theta JA}(t \leq 10s)$	20	$^{\circ}\text{C}/\text{W}$
	$R_{\theta JA}(\text{Steady State})$	55	$^{\circ}\text{C}/\text{W}$
Thermal Resistance-Junction to Case (note2)	$R_{\theta JC}$	2	$^{\circ}\text{C}/\text{W}$
Maximum Junction Temperature	T_J	150	$^{\circ}\text{C}$
Storage Temperature Range	T_{STG}	-55 to 150	$^{\circ}\text{C}$
Avalanche Current, Single pulse	$I_{AS}(L=0.5\text{mH})$	24	A
Avalanche Energy, Single pulse	$E_{AS}(L=0.5\text{mH})$	144	mJ

ELECTRICAL CHARACTERISTICS ($T_A=25^{\circ}\text{C}$ unless otherwise noted)

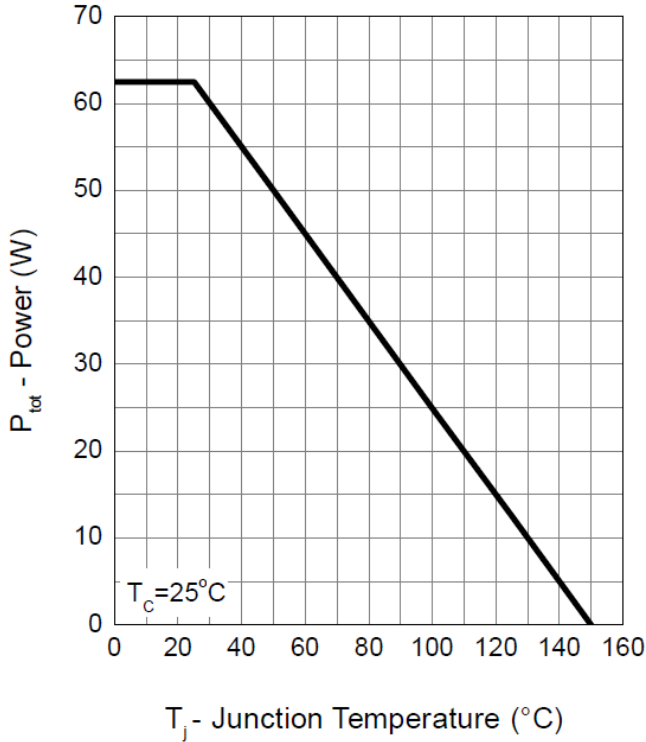
Parameter	Symbol	Test Conditions	Min	Typ	Max	Unit
STATIC CHARACTERISTICS						
Drain-Source Breakdown Voltage	BV_{DSS}	$V_{GS}=0V, I_D=-250\mu A$	-30	-	-	V
Zero Gate Voltage Drain Current	I_{DSS}	$V_{DS}=-24, V_{GS}=0V$	-	-	-1	μA
Gate-Body Leakage Current	I_{GSS}	$V_{GS}=\pm 20V, V_{DS}=0V$	-	-	± 10	μA
ON CHARACTERISTICS (Note 3)						
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS}=V_{GS}, I_D=-250\mu A$	-1.3	-1.8	-2.3	V
Drain-Source On-State Resistance	$R_{DS(ON)}$	$V_{GS}=-4.5V, I_{DS}=-10A$	-	11	15	m Ω
		$V_{GS}=-10V, I_{DS}=-20A$	-	7	9	m Ω
DYNAMIC CHARACTERISTICS (Note 4)						
Gate Resistance	R_g	$V_{GS}=0V, V_{DS}=0V, F=1MHz$	-	8	-	Ω
Input Capacitance	C_{iss}	$V_{DS}=-15V, V_{GS}=0V, F=1.0MHz$	-	2110	-	PF
Output Capacitance	C_{oss}		-	460	-	PF
Reverse Transfer Capacitance	C_{rss}		-	360	-	PF
SWITCHING CHARACTERISTICS (Note 4)						
Turn-on Delay Time	$t_{d(on)}$	$V_{DD}=-15V, R_L=15\Omega, V_{GEN}=-10V, R_G=6\Omega, I_{DS}=-1A$	-	12	-	nS
Turn-on Rise Time	t_r		-	12	-	nS
Turn-Off Delay Time	$t_{d(off)}$		-	110	-	nS
Turn-Off Fall Time	t_f		-	68	-	nS
Total Gate Charge	Q_g	$V_{DS}=-15V, I_{DS}=-20A, V_{GS}=-10V$	-	47	-	nC
Gate-Source Charge	Q_{gs}		-	3	-	nC
Gate-Drain Charge	Q_{gd}		-	15	-	nC
Body Diode Reverse Recovery Time	T_{rr}	$I_{DS}=-20A, di/dt=100A/\mu s$	-	16	-	nS
Body Diode Reverse Recovery Charge	Q_{rr}		-	5	-	nC
DRAIN-SOURCE DIODE CHARACTERISTICS						
Diode Forward Voltage (Note 3)	V_{SD}	$V_{GS}=0V, I_{SD}=-1A$	-	-0.7	-1	V

NOTES:

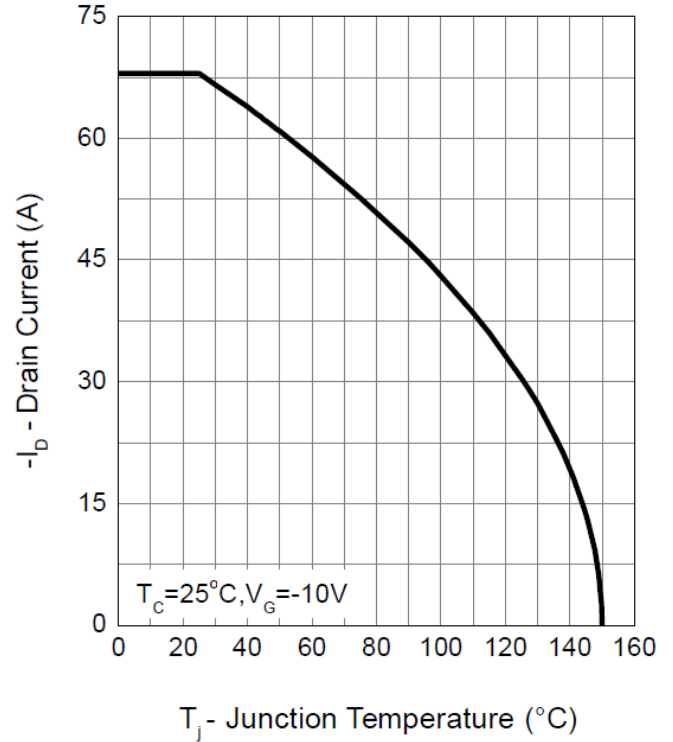
- Surface Mounted on 1in^2 pad area, $t_s \leq 10\text{sec}$. $R_{\theta JA}$ steady state $t = 999s$.
- The power dissipation P_D is based on $T_{J(MAX)} = 150^{\circ}\text{C}$, and it is useful for reducing junction-to-case thermal resistance ($R_{\theta JC}$) when additional heat sink is used.
- Pulse Test: Pulse Width $\leq 300\mu s$, Duty Cycle $\leq 2\%$.
- Guaranteed by design, not subject to production testing

Typical Operating Characteristics

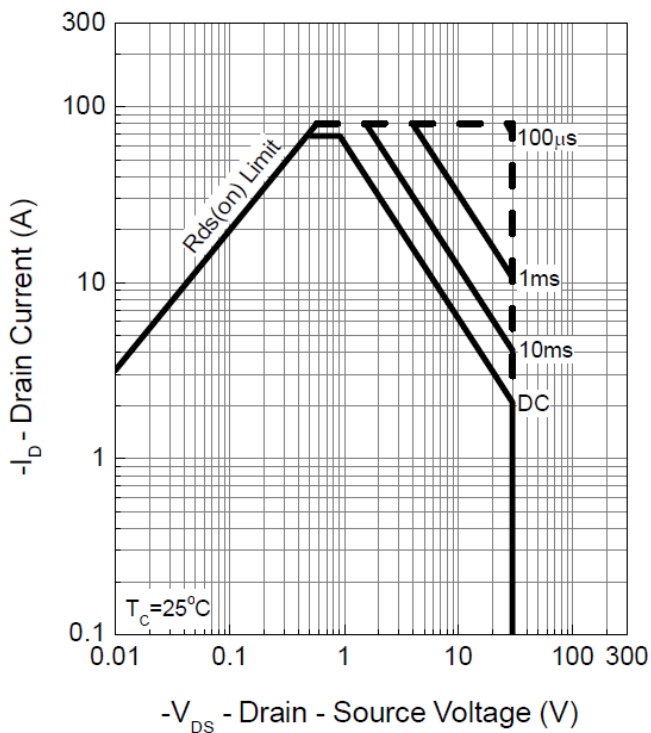
Power Dissipation



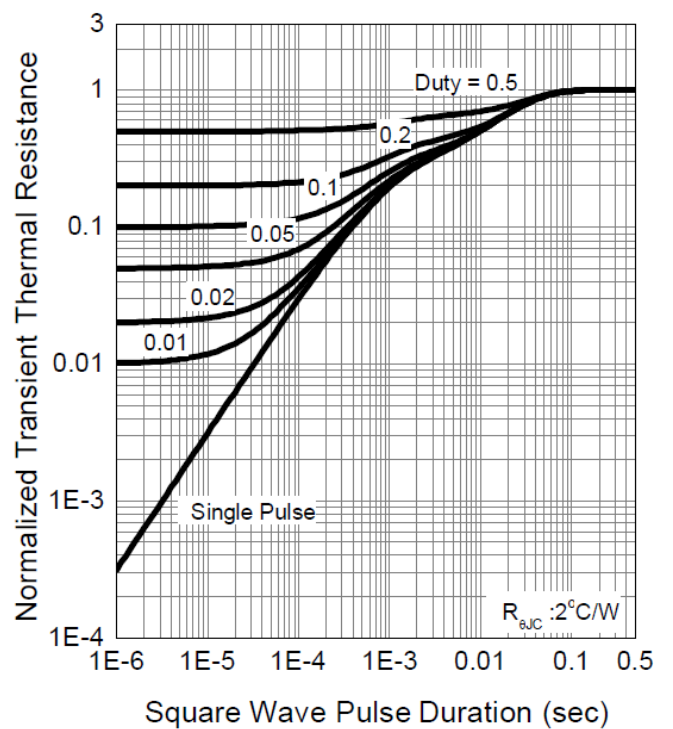
Drain Current



Safe Operation Area

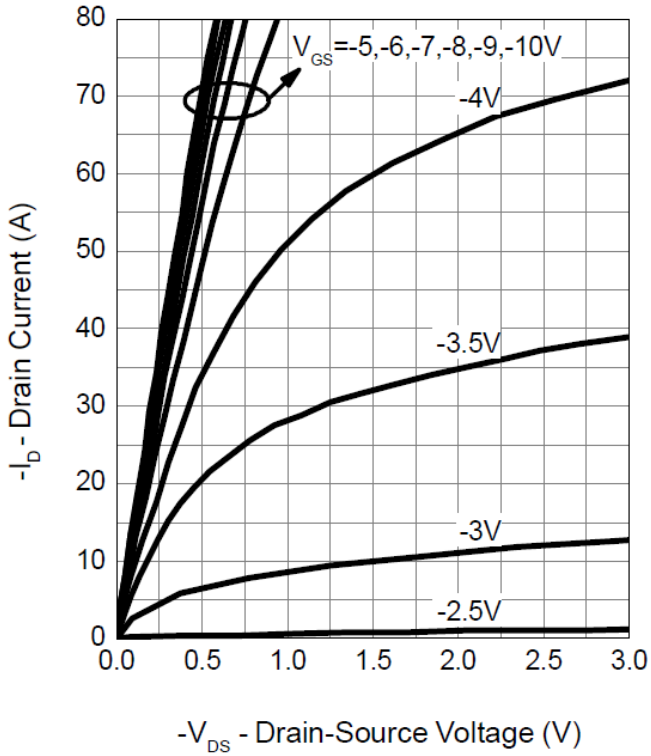


Thermal Transient Impedance

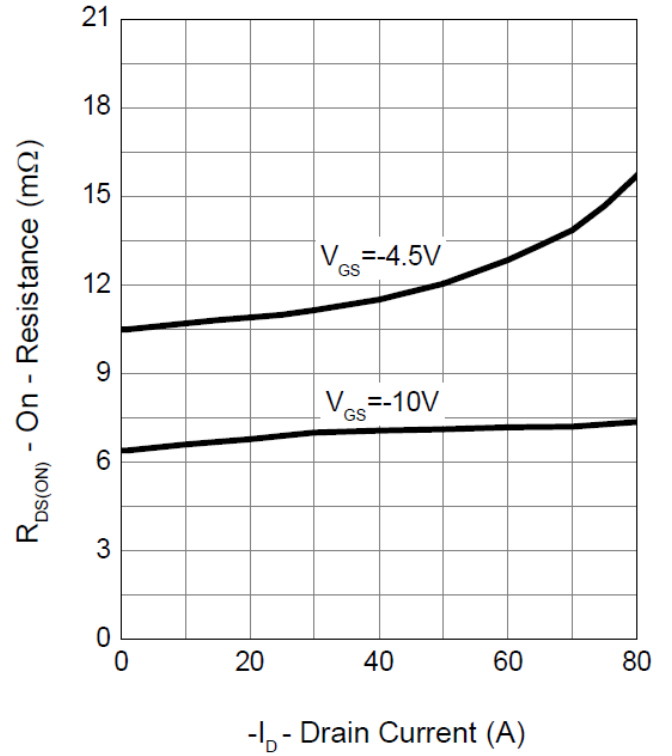


Typical Operating Characteristics(Cont.)

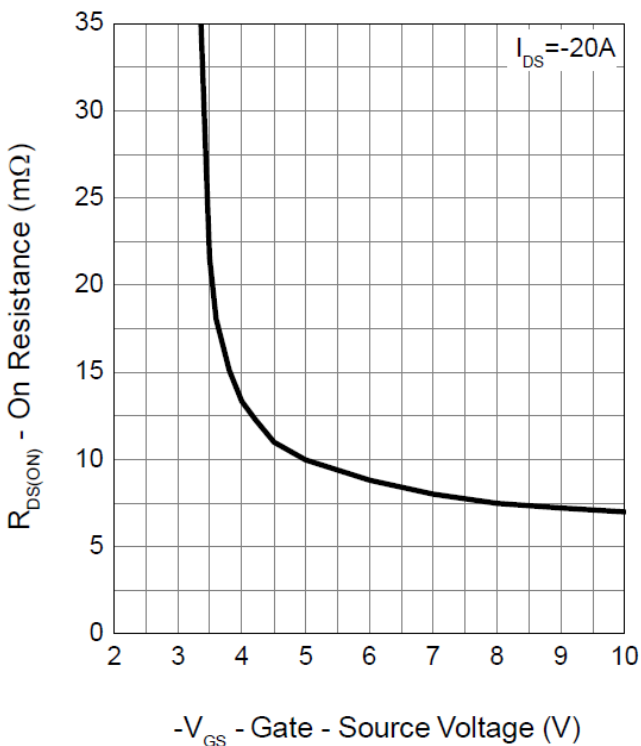
Output Characteristics



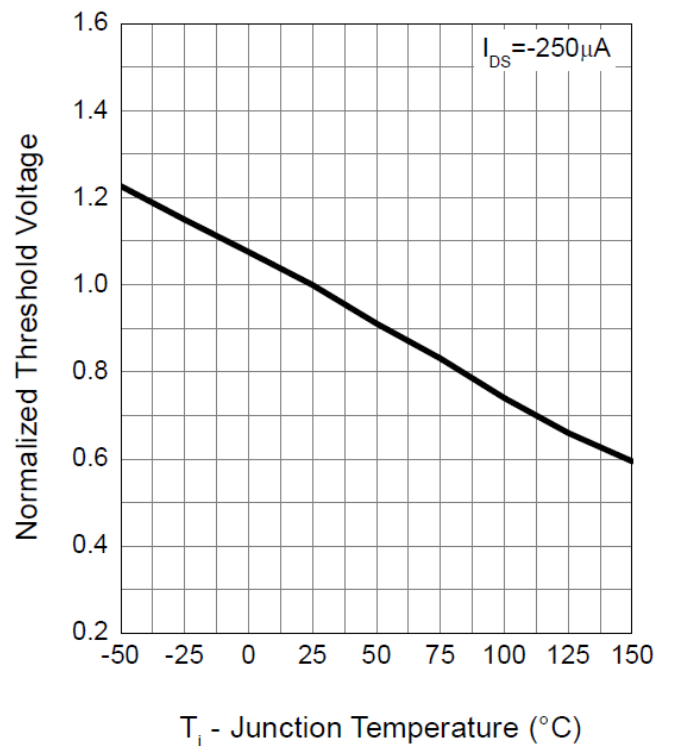
Drain-Source On Resistance



Gate-Source On Resistance

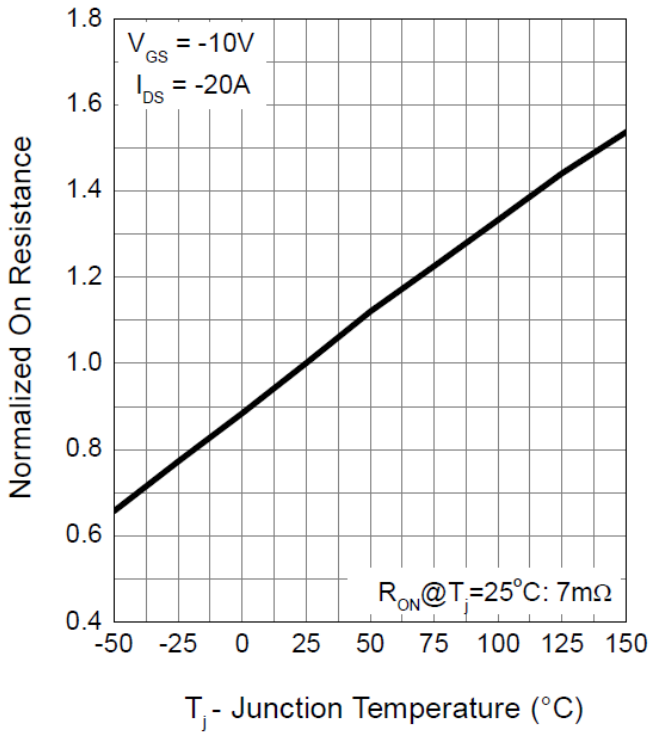


Gate Threshold Voltage

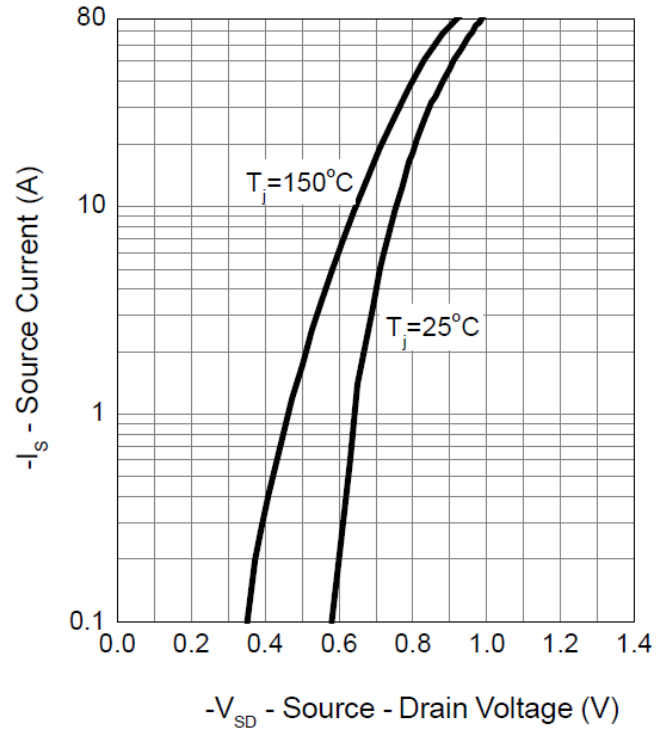


Typical Operating Characteristics (Cont.)

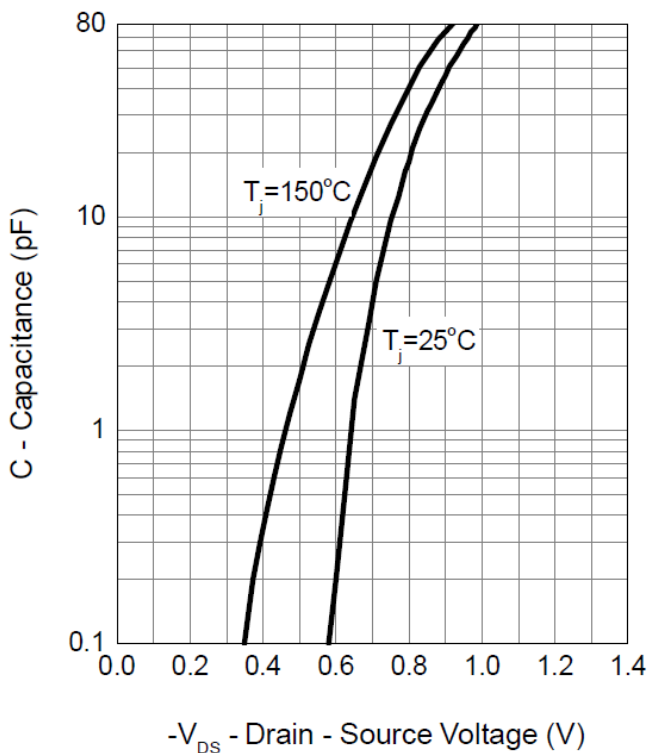
Drain-Source On Resistance



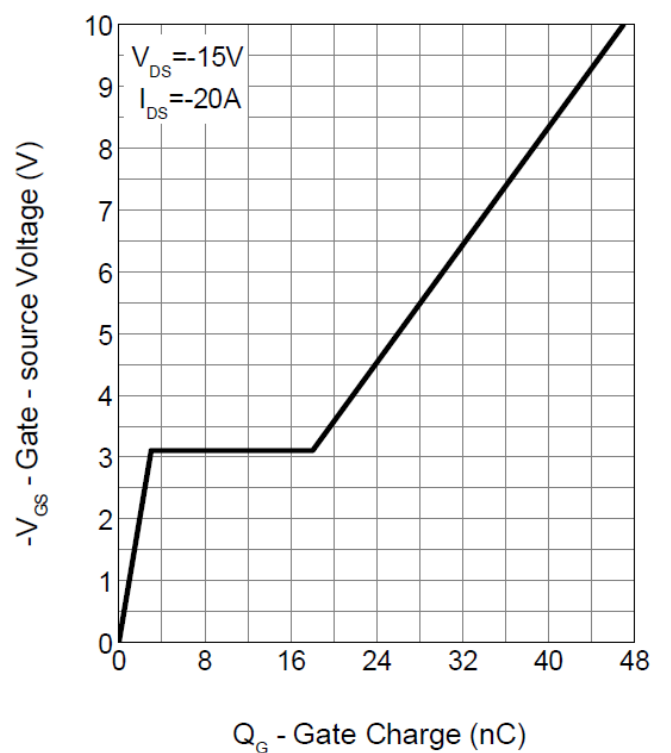
Source-Drain Diode Forward



Capacitance

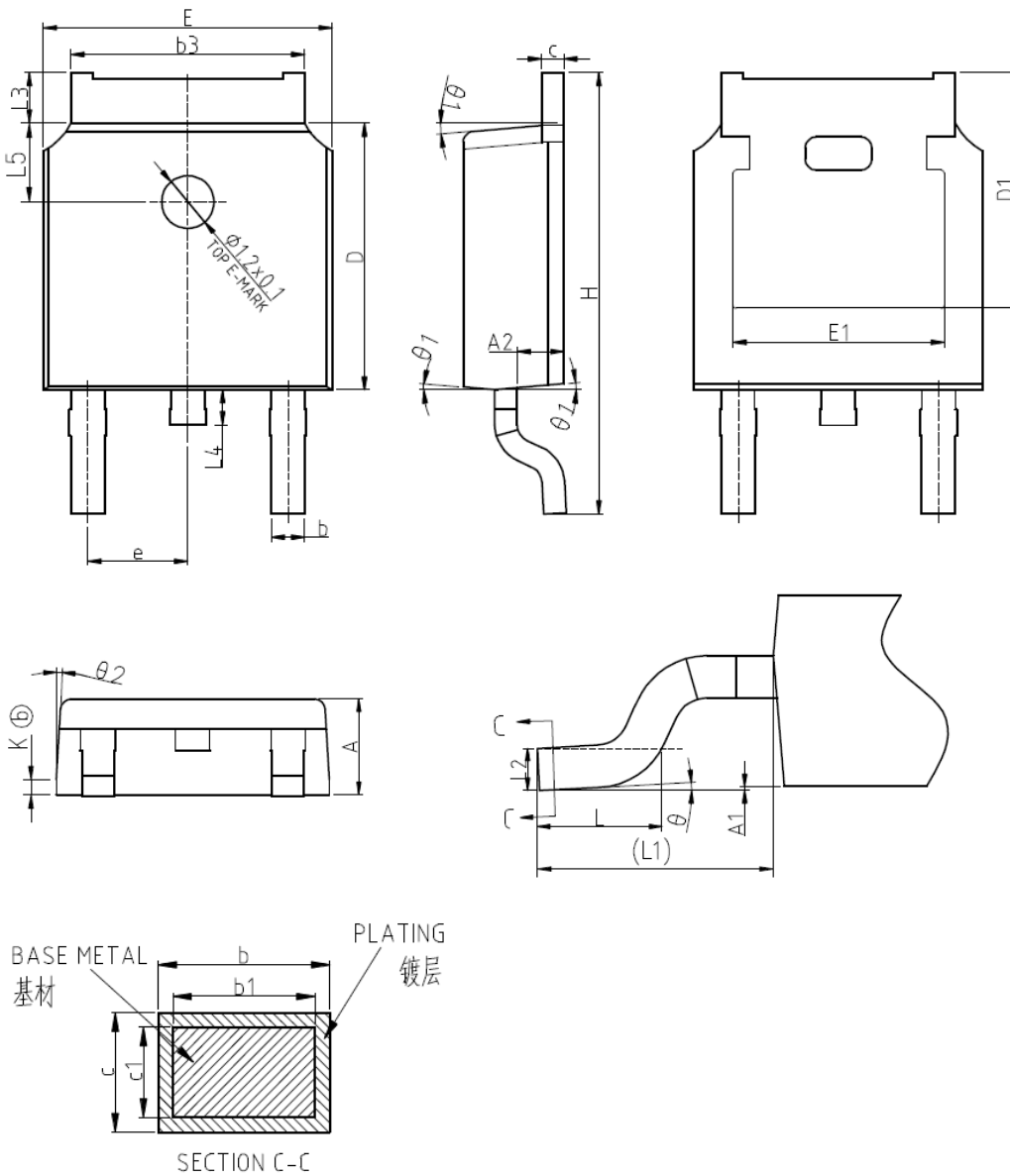


Gate Charge



Package Information

TO252-3 Package



SYMBOL	mm		
	MIN	NOM	MAX
A	2.20	2.30	2.40
A1	0.00	-	0.20
A2	0.97	1.07	1.17
b	0.68	0.78	0.90
b1	0.66	0.76	0.88
b3	5.20	5.33	5.50
c	0.43	0.53	0.63
c1	0.41	0.51	0.61
D	5.98	6.10	6.22
D1	5.30REF		
E	6.40	6.60	6.80
E1	4.63	4.83	5.03
e	2.286BSC		
H	9.40	10.10	10.50
L	1.38	1.50	1.75
L1	2.90REF		
L2	0.51BSC		
L3	0.88	-	1.28
L4	-	-	1.00
L5	1.65	1.80	1.95
θ	0°	-	8°
θ1	5°	7°	9°
θ2	5°	7°	9°
K	0.40REF		

Design Notes